**Introduction of CYTOP S type adhesion method (for spin coating)**

The CYTOP S type has excellent mold release. If it is applied directly to a substrate, it can be peeled off easily. To attach the S type to a substrate, the following processing method is recommended.

1. **Apply silane coupling agent** *1 and perform spin coating.**
   - Spin condition: 500 rpm for 15 sec. + 4000 rpm for 20 sec.
   - *1 Silane coupling agent
     - "KBE-903" by Shin-Etsu Chemical Co., Ltd.
     - "SILA-ACE S330" by Chisso Corporation, etc.

2. **CTL-809A is diluted to 0.5% and spin coating is performed.**
   - Spin conditions: 500 rpm for 5 sec. + 1000 rpm for 30 sec.

3. **50°C x 30 min. baking**
   - It must be stopped in a semi-dry condition. (If it is completely dry, adhesive power is low.)

4. **CTX-809SP2 is diluted to 5% and spin coating is performed.**
   - Spin condition: 500 rpm for 5 sec. + 1000 rpm for 30 sec.

5. **Drying at room temperature: 5 to 30 min.**
   - (Prebaking [degas]: 50°C x 10 to 30 min.)
   - * If the film is thin (5 μm or less), this process is not required.
   - Prebaking [removal of solvent]: 80°C x 30 to 60 min.
   - Final baking: 180 to 250°C x 30 to 60 min.